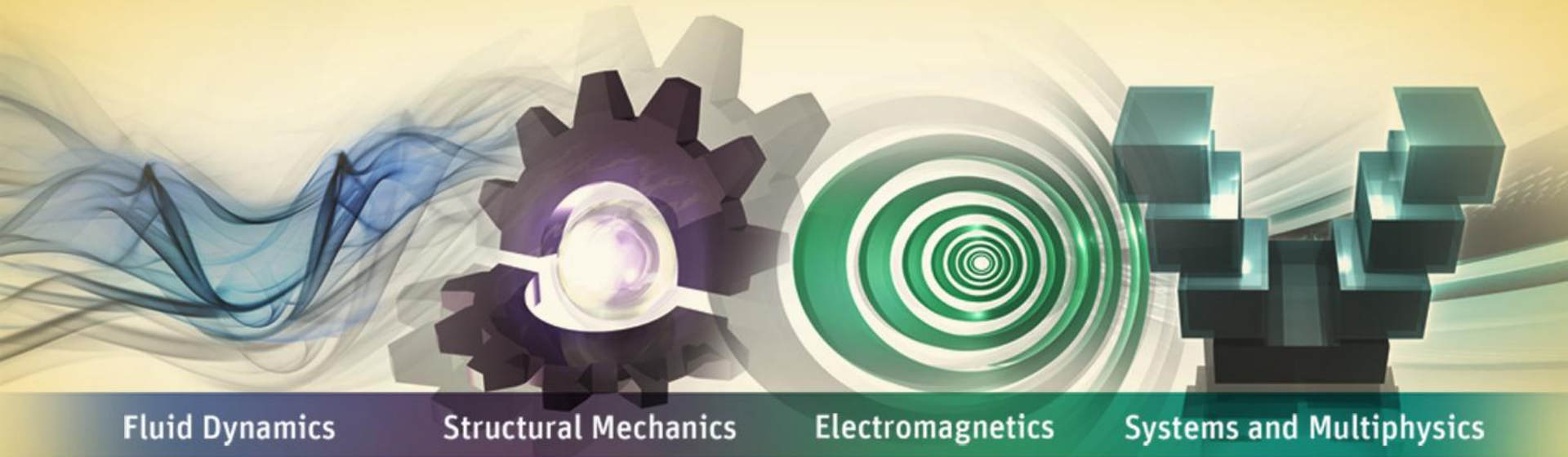


Multiphysics Modeling and Simulation for Armament System Improvement



Fluid Dynamics

Structural Mechanics

Electromagnetics

Systems and Multiphysics

Bill McGinn

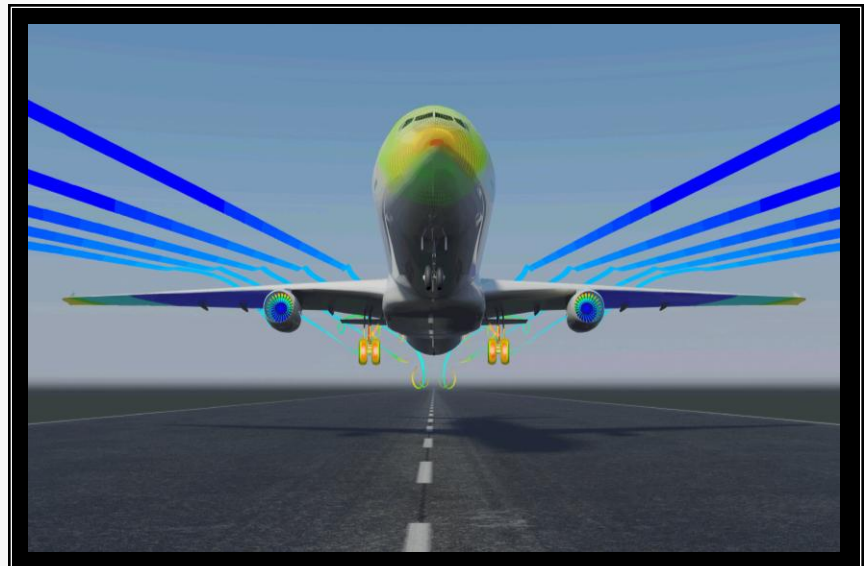
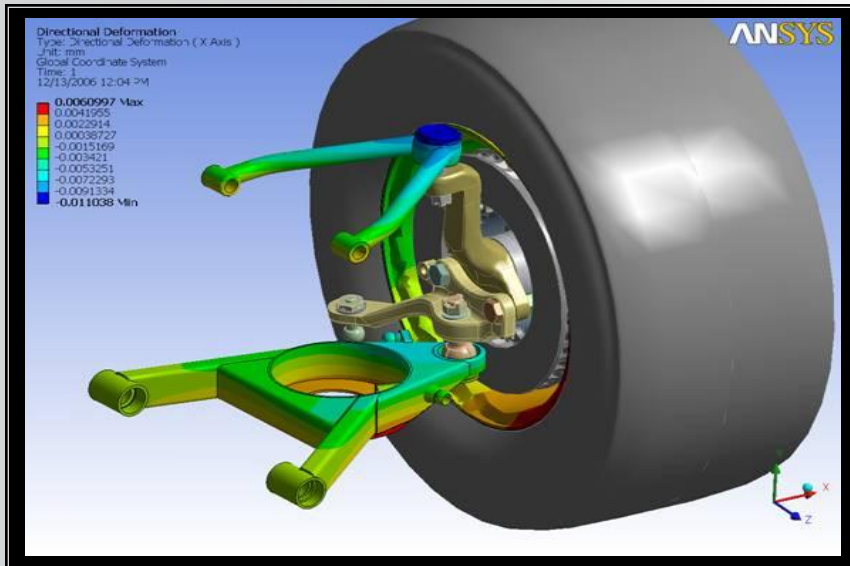
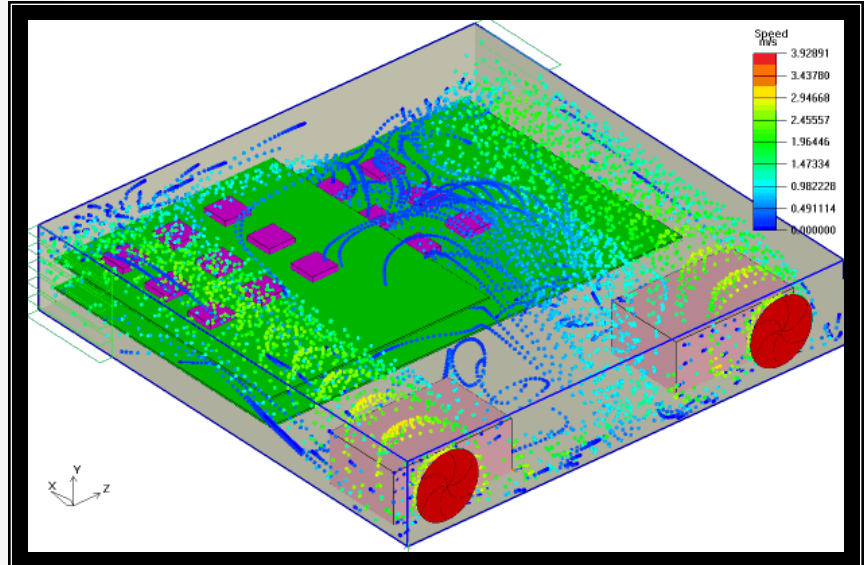
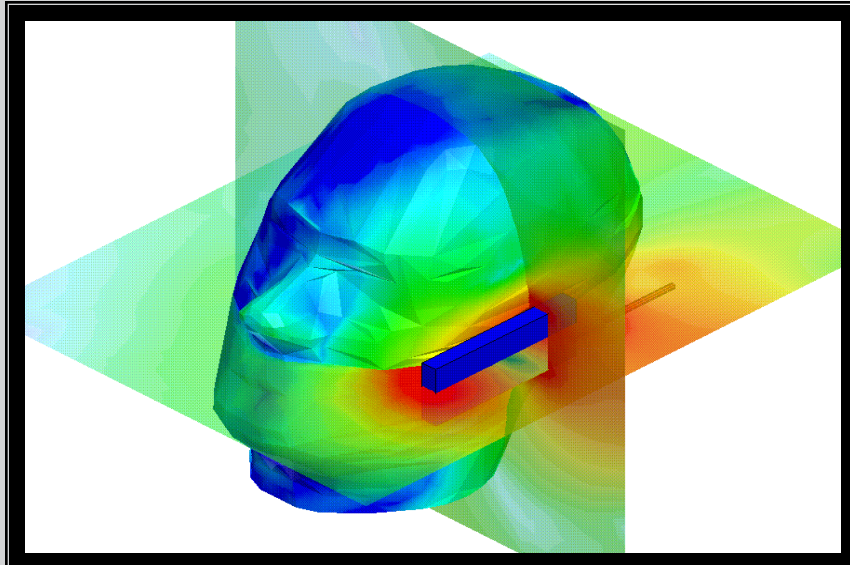
Lead Application Engineer

ANSYS, Inc

Bill.Mcginn@ansys.com

Physics-Based Simulation

Electromagnetics, Thermal, Structural Mechanics, Fluid Dynamics



- **Industry Trends**

Industry Trends Are Reshaping A&D Product Development



Rising Fuel Costs



Safety and Environmental Considerations



New Space Race



Fiscal Constraints



Geopolitical Drivers



Warfare Revolution

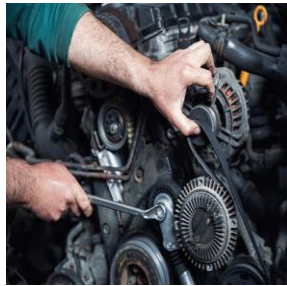
-
- **Key Implications**
-

*Constricting Defense Budgets Cause Focus On Affordability, Reduction In New Procurement And The Extension Of The Service Life Of Equipment---
Need to design for **Affordability***



Fiscal Constraint

Something that is
tion or feeling of
Fights between
child and producti
productivity /p
efficiency of a co
lated by compari
produced with the



- Do more without more
- Shift from procurement to sustainment

Key Business Initiatives

- Design for Affordability
- Engineer for Sustainment

*Commercial And Military Competition Drives Innovation And Increases The Pressure On Deployment Timeframe --- Need to Design and Implement systems **Faster**.*



Geopolitical Drivers



- **Emerging competition in commercial aero and space**



- **System Sophistication**



- **Heavy investment in defense technologies in emerging markets**

Key Business Initiatives

- Faster Design Cycles
- Commercial design practices
- Employ up-front analysis

*As The Nature Of Warfare Changes, The Demand For Intelligence, Surveillance And Reconnaissance (ISR) Technology Is Increasing Significantly --- Need to develop **Smart** systems*



Warfare Revolution



- **Field recognition of the importance of novel ISR capabilities**

- **More sophisticated, robust and affordable unmanned systems**

- **Increase sensor complexity**

- **Manage size, weight and power (SWaP)**

Key Business Initiatives

- Design in more intelligence
- Increased use of electronics
- Increased need for Multiphysics evaluation

Industry trends are driving the development of more sophisticated electronic systems in shorter time frames and with greater fiscal scrutiny

Fiscal constraint, coupled with the increasing demands of sophistication, competition and time pressure mean that system robustness is more important than ever

Working with thousands of customers around the globe, we (Ansys) observe industry leaders adopting best practices to tackle robust design through simulation based engineering

Simulation based engineering is a key enabler for Robust design using Accurate, Multi-Physics based analysis tools.

-
- Multi-Physics Simulation
-

Why is multiphysics based design a best practice for robustness and affordability?

Raytheon
Customer Success Is Our Mission

AIR
LAND
SEA
SPACE
CYBER

Multi-Physics Application
Coupled Electrical, Thermal, and Stress
Analysis of High Power Antenna and
Microwave Components

Amedeo Larussi
Sr. Principal Electrical Engineer
August 27, 2013

11th Annual Military Antennas
Web Based Presentation
September 17 - 18, 2013 - Washington Plaza, Washington, District of Columbia

TPCR-SAS 5211 (Approved-8/13/2013)

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Amedeo Larussi
Sr Principal Electrical Engineer
Raytheon Space and Airborne Systems

“Traditional engineering methods are not able to accurately anticipate performance degradation and /or product failures because does not combine all performance factors”

Raytheon
Space and Airborne Systems

Multi-Physics Coupled Method

Coupled EM/Thermal Example
Solve EM; export EM mesh to thermal; solve thermal, update EM material properties based on thermal temperature, solve updated EM model, etc.
The ability to import an d/or export simulation mesh among the above engineering disciplines will result in relevant improvement in system performance prediction.

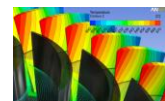
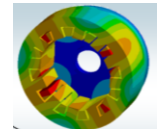
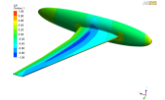
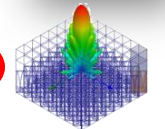
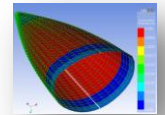
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9/17/2013 | 7

Idga/webinars

ANSYS's Aerospace and Defense Best Practices Derived from Cross-Industry Knowledge Bring Best-In-Class Insights to Solve Your Product Development Challenges

ANSYS's Cross-Industry Best Practices	ANSYS's A&D Best Practices
Advanced Lightweight Materials Design	Efficient Design Of Lightweight Composites For Multifunctional Applications
Robust Electrical and Electronics System Design	Integrated Multiphysics Simulations for Robust Platform-Payload Integration
Fluid Structure Interaction	Integrated Multiphysics Simulations for Emerging Aeroelastic Challenges
Electric Machine Design	Robust, Efficient Electric Machine Design for the More Electric Aircraft
Fluid-Thermal System Design	Reduce Fuel Burn Through the Design Of More Efficient Engines



The Workbench Environment



Coupled Physics Solutions
•Automated geometry transfer and data exchange of solution shown by connections

CAD Geometry

Available Physics

The screenshot shows the ANSYS Workbench interface for a project named 'Full_F16_AIRCRAFT'. The 'Project Schematic' area contains five analysis systems: A (Geometry), B (HFSS Design), C (Steady-State Thermal), D (Static Structural), and E (Response Surface). System A is highlighted with a red box and labeled 'CAD Geometry'. System E is also highlighted with a red box and labeled 'Response Surface'. A 'Parameter Set' is located below the schematic. Blue arrows indicate data flow from A to B, B to C, and C to D. Red arrows indicate data flow from B, C, and D to the Parameter Set. A red box highlights the connections between B, C, and D, labeled 'Coupled Physics Solutions'. A red arrow points from the 'Available Physics' label to the Toolbox on the left. A 'Design Exploration' table is visible at the bottom of the interface.

Progress	A	B	C
1	Status	Details	Progress

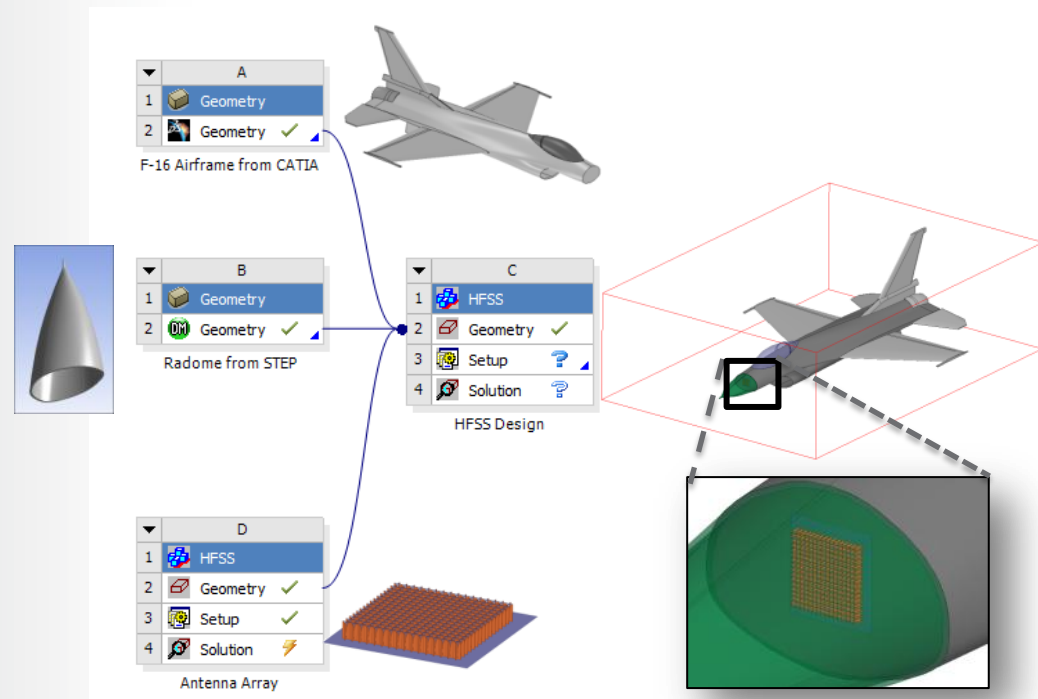
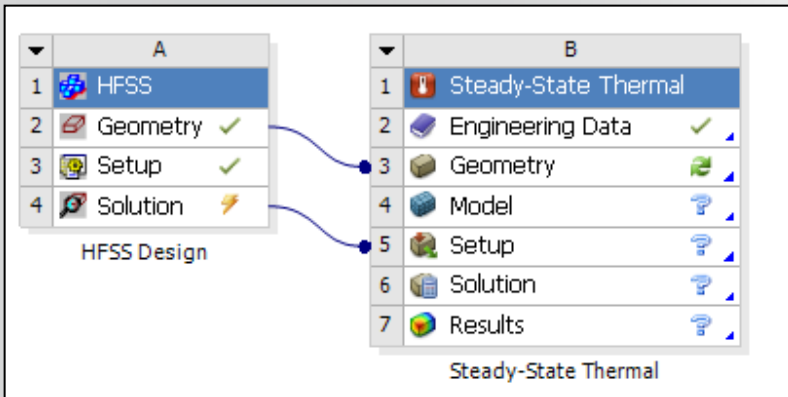
Parameter Set
•Controls inputs and views outputs of each simulation, i.e. Input = Antenna Scan Angle, Output = Max Radome Deformation

Design Exploration

ANSYS Workbench Integration Benefits

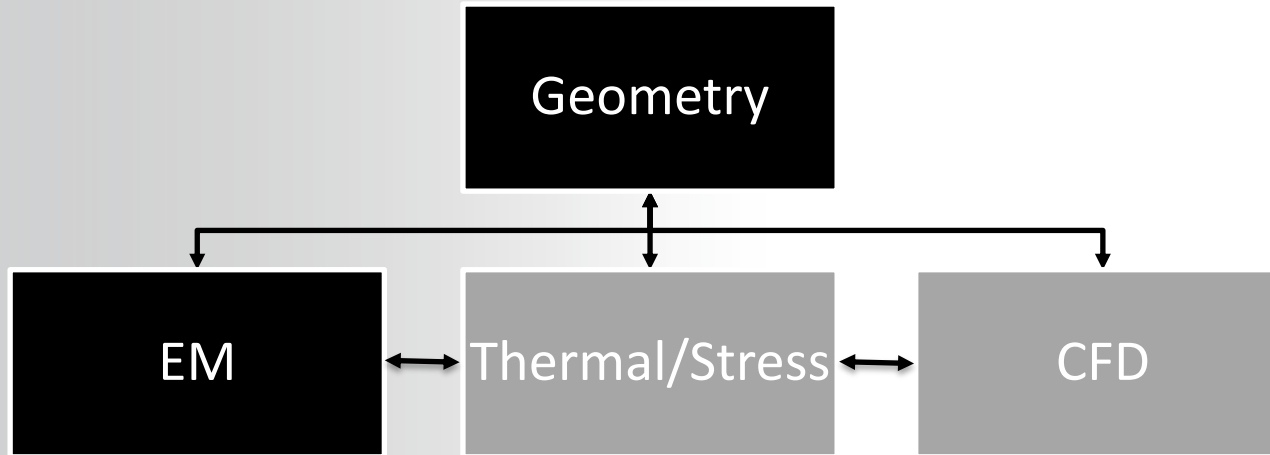
Benefits of Integration

- Utilizes intuitive multi-physics layout
 - Automated data exchange
 - Coupled physics solutions
- Efficient system design exploration
- Streamlined geometry handling
 - CAD integration in ANSYS Workbench provides bi-directional link to 3rd party CAD tools
 - Multiple physics can share the common geometry



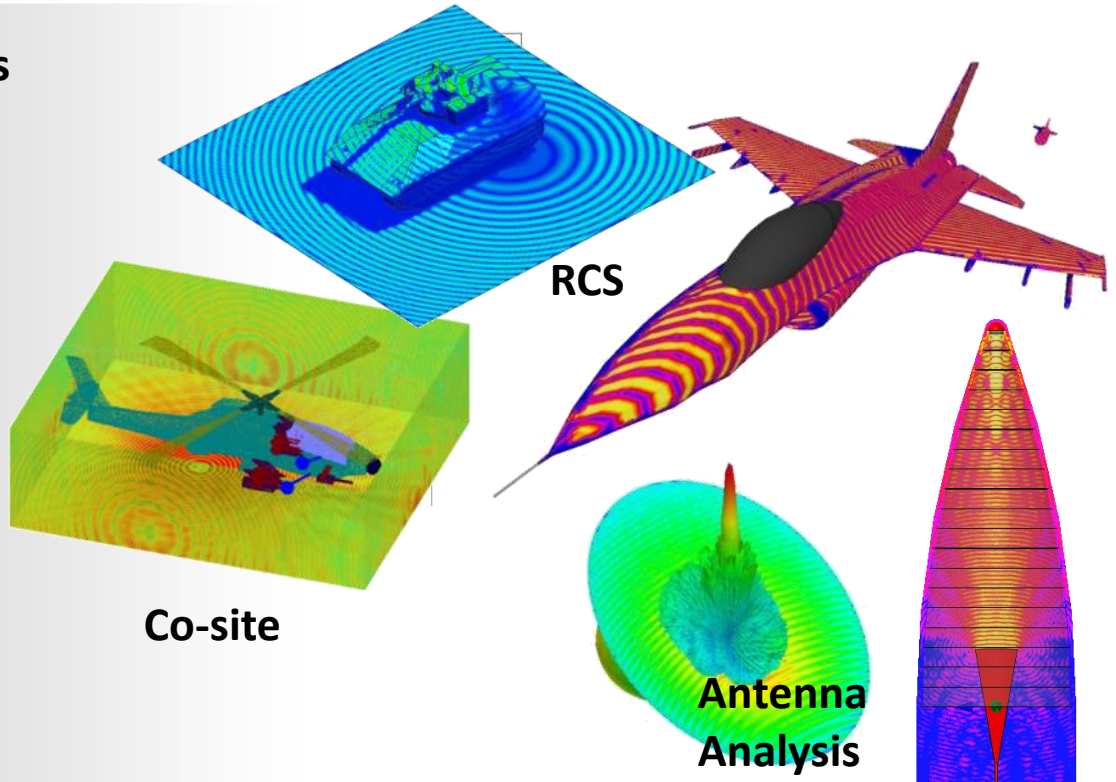
Electromagnetic Solutions

ANSYS®



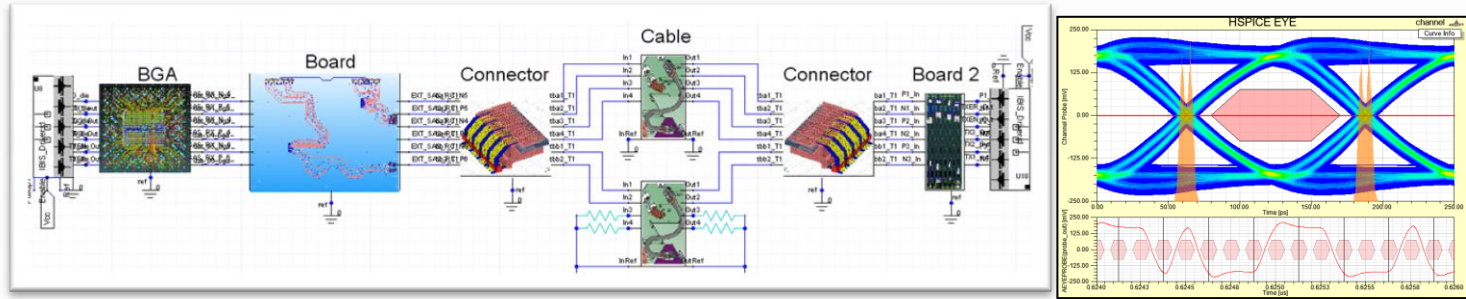
- Overview ANSYS EM Capabilities

- FEM, IE, PO, hybrid solvers
- RCS
- Antenna Placement/Co-Site Analysis
- Antenna Array
 - Unit Cell and Finite Array Analysis
 - Array Platform Analysis
- Feed Network

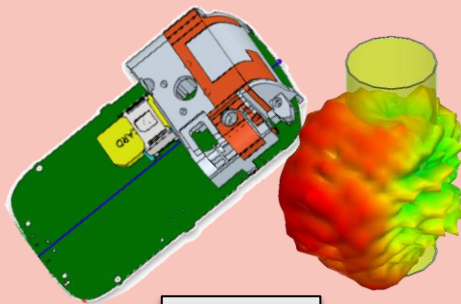


Electronics Applications

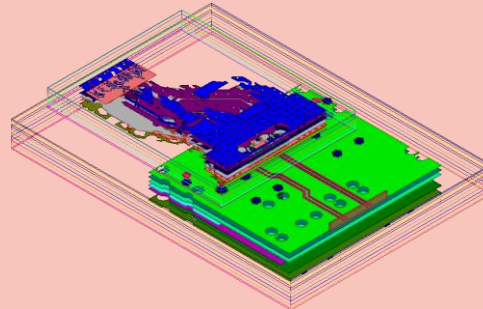
Circuit & System Design



RF and SI Physical Design



Antennas

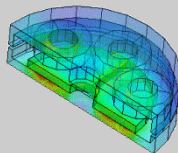
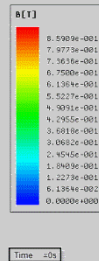


Package/PCB

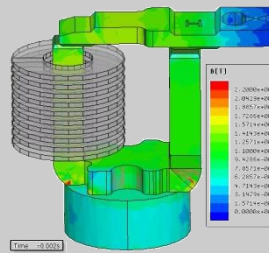


EMI/EMC

Electromechanical Design

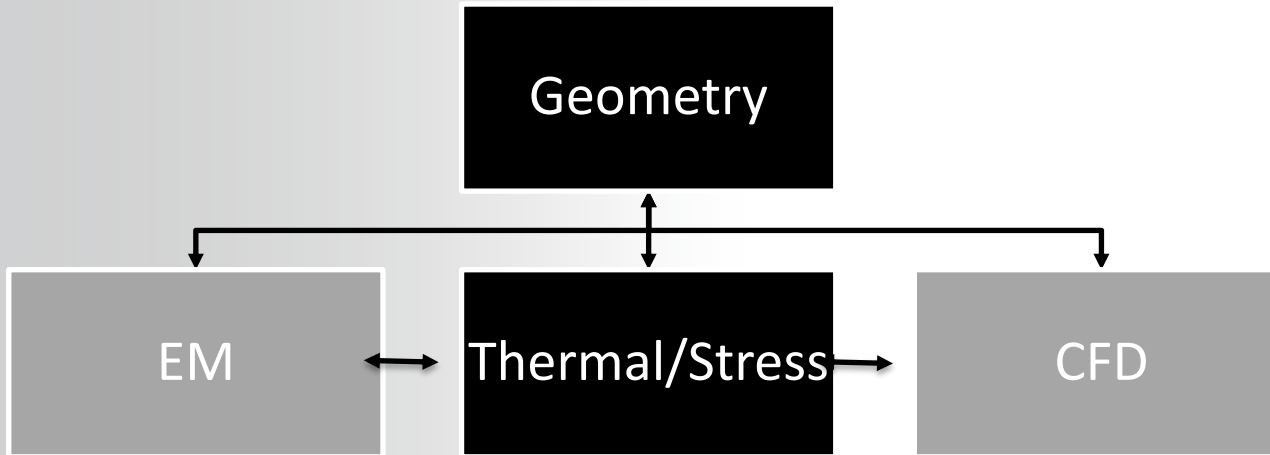


Motors/Actuators



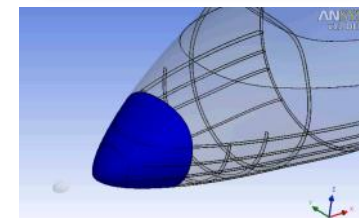
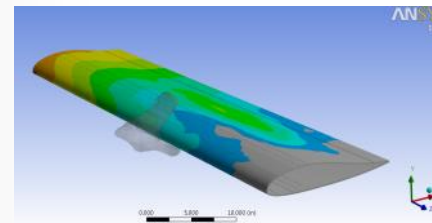
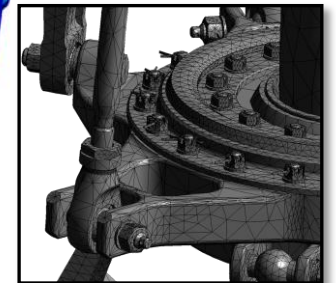
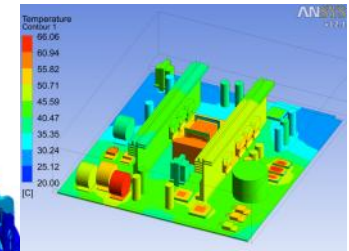
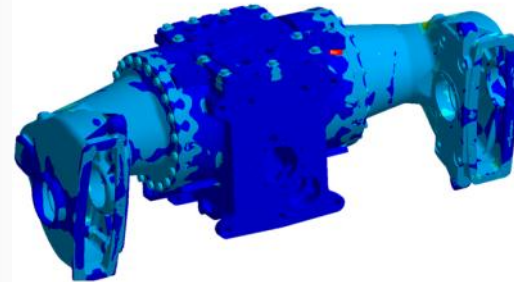
Power Electronics

Mechanical Solutions

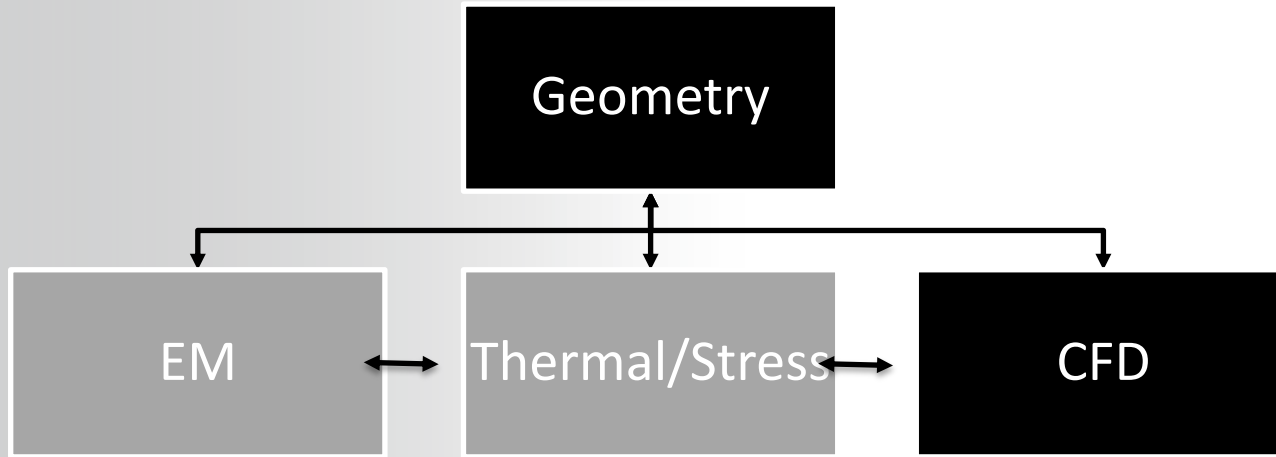


- Overview ANSYS Mechanical Capabilities

- Steady State/Transient
- Explicit Solvers (Impact)
- Solid, Shell, Beam, and Point Mass Elements
- Convection/Conduction/Radiation/Advection
- Layered Composite Shells and Solids
- Automatic Contact Setup (Thermal and Structural)
- HPC for large model support

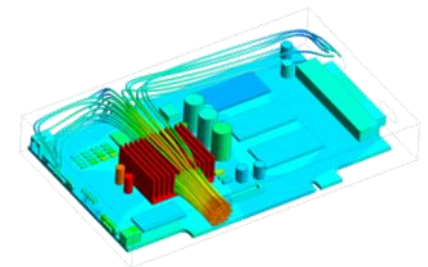
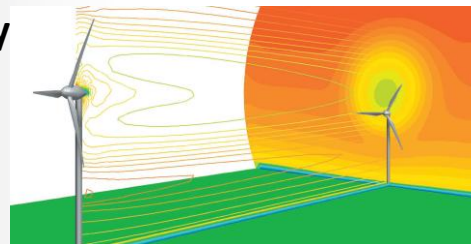
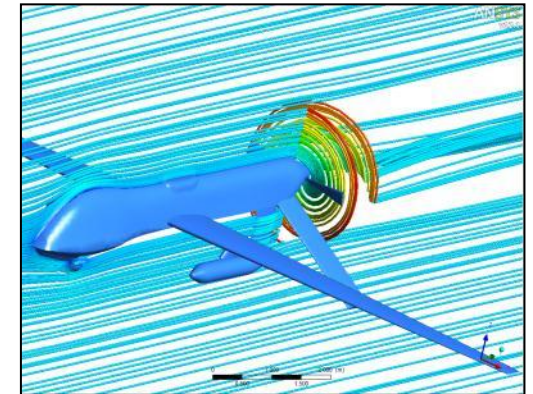
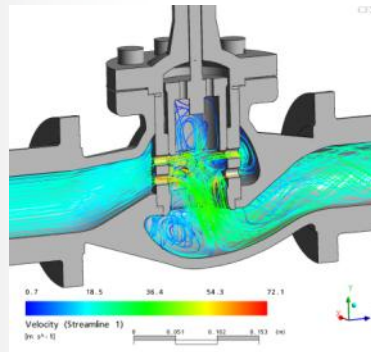


Computational Fluid Dynamics Solutions

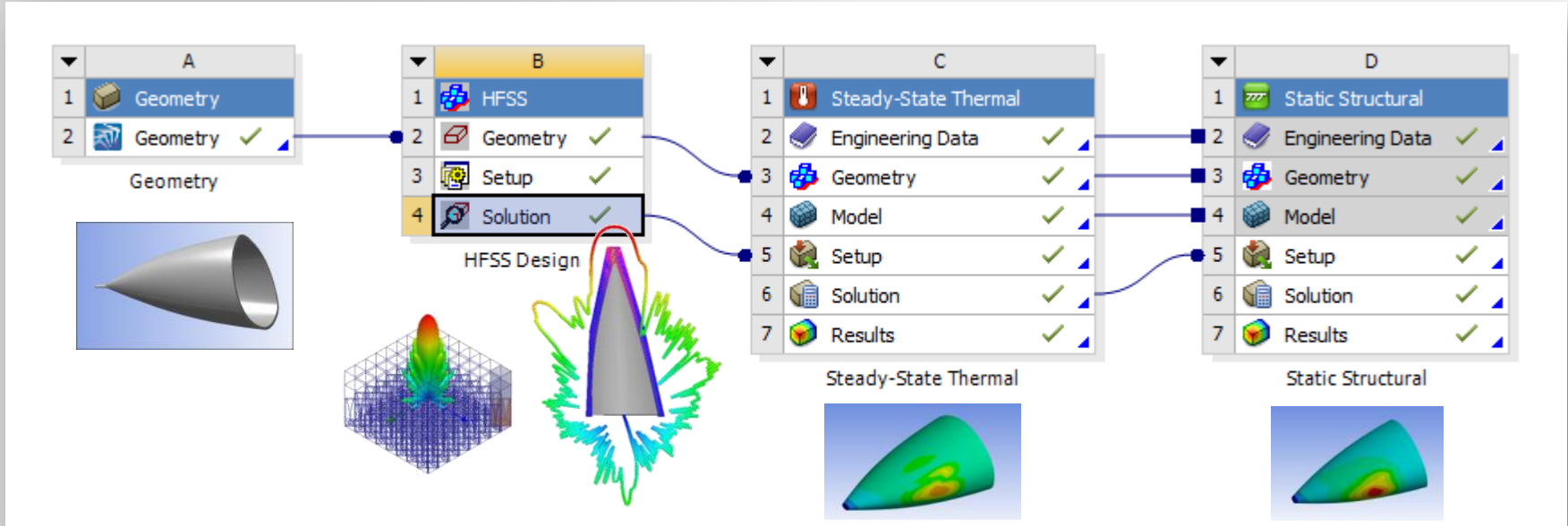


• Overview of CFD Capabilities

- Incompressible/Compressible Flow
- Extensive Turbulence Models
- Multi-Species & Reacting Flow
- Conjugate Heat Transfer
- Fluid Structure Interaction – 1 way & 2 way
- Dynamic, moving & sliding meshes



Radome and Antenna Multi-Physics Example: Workbench Project



Geometry

- Bi-Directional Link to most CAD tools
- Radome geometry from CAD can be used for all physics

EM Analysis

- HFSS
- Data link antenna pattern and Radome

Thermal Analysis

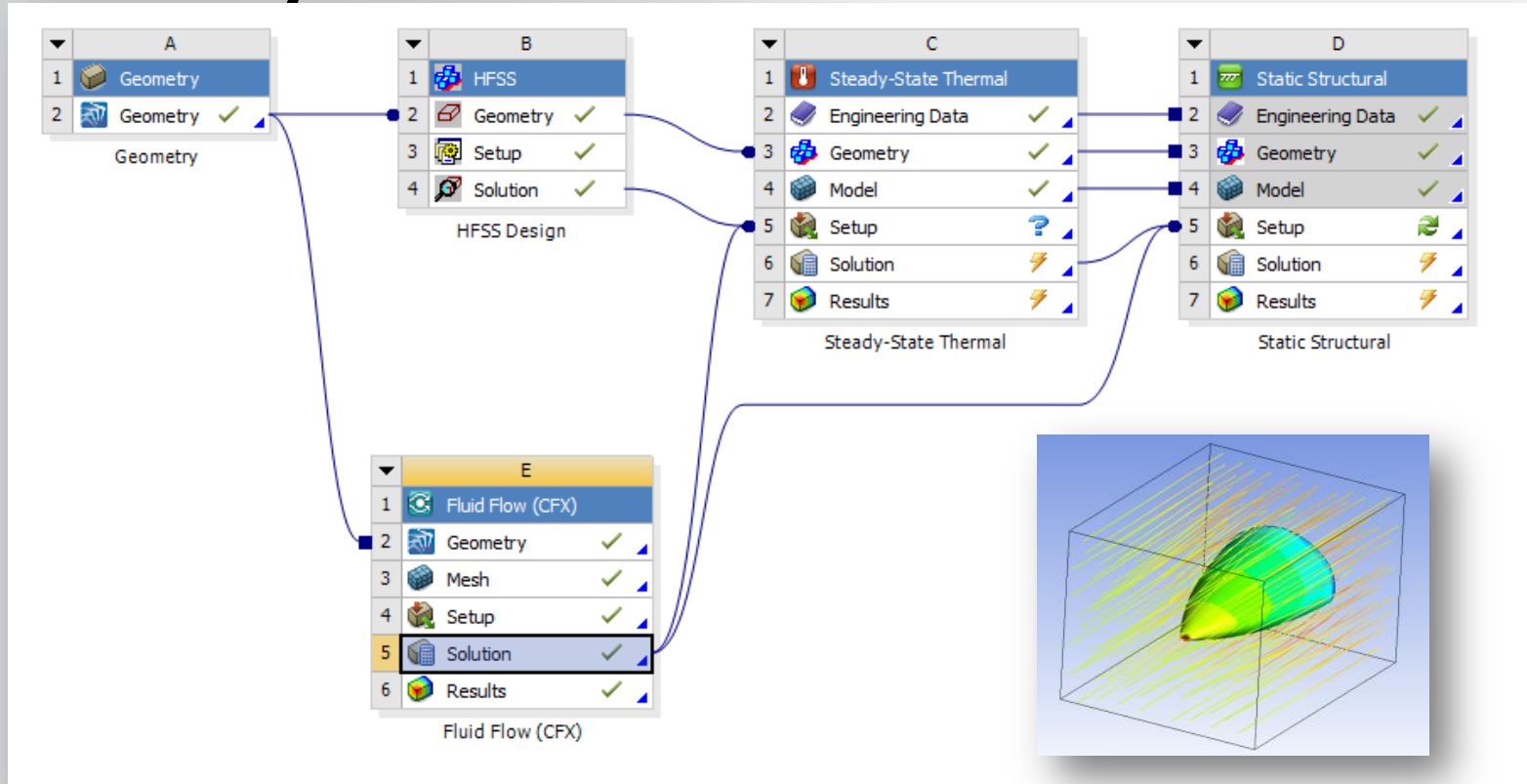
- Ansys Mechanical
- Boundary conditions for convection and other thermal properties applied

Structural Analysis

- Ansys Mechanical
- Structural boundary conditions and any external loads can be added

Generic geometry source: <http://www.3dcontentcentral.com/parts/browse/Aircraft/User-Library/136/136/Models/part.aspx?id=12463#1>

Incorporating Fluid Dynamics into Multi-Physics Simulation Flow



Steady State Thermal and CFD -

Convection coefficients determined from CFD solution

Static Structural and CFD -

Pressure/forces mapped from CFD solution impacting geometry deformation

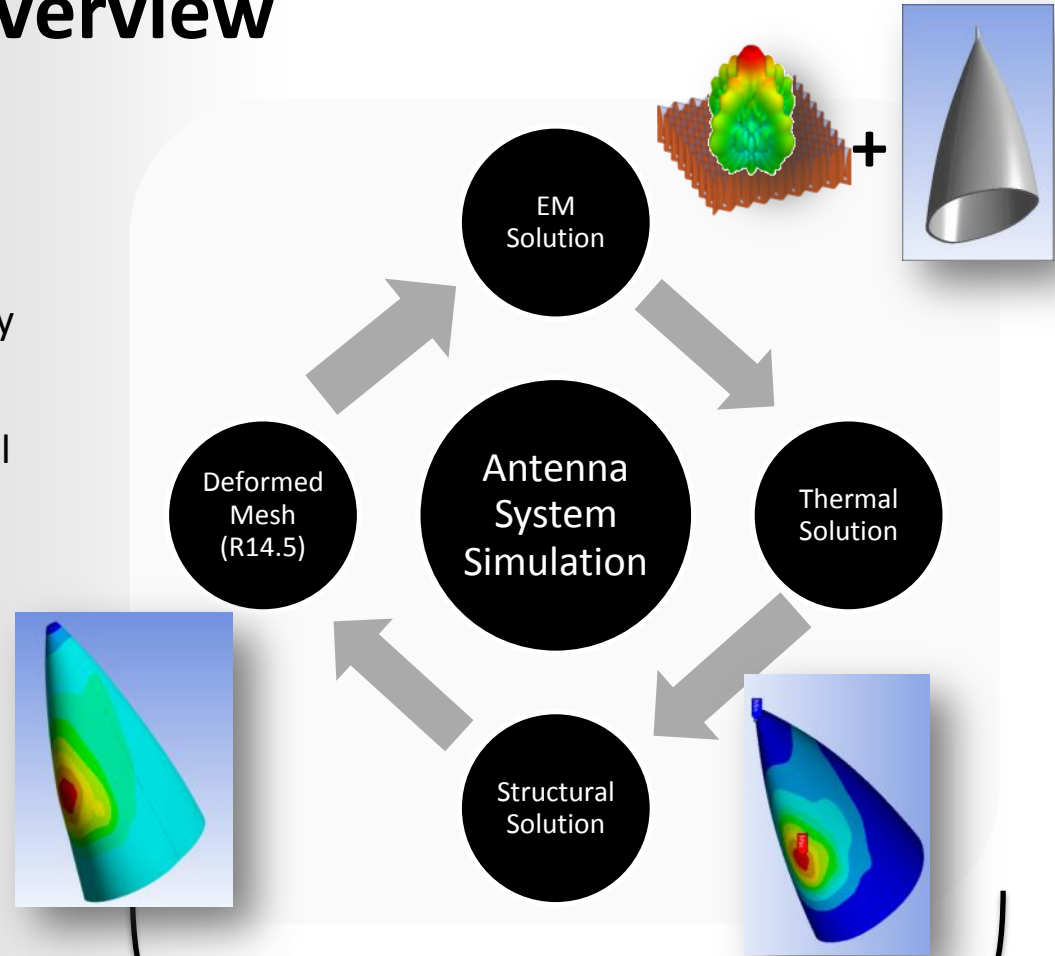
Simulation Flow – HFSS/Thermal/Structural Simulation Overview

• Antenna and Radome Simulation Flow

- EM Solution of Antenna Array
- EM Solution of Radome using array solution as excitation (data link)
- Losses passed to Ansys Mechanical for thermal analysis
- Thermal loading applied to structural solution to calculate deformation

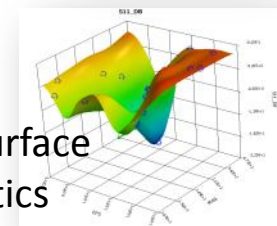
• Antenna System Simulation Iterations

- Temperature Dependent Material properties can be applied in EM solution
- Mesh Deformations (v14.5)



Design Exploration

- DOE Based Response Surface
- 6 σ , Optimization, Statistics



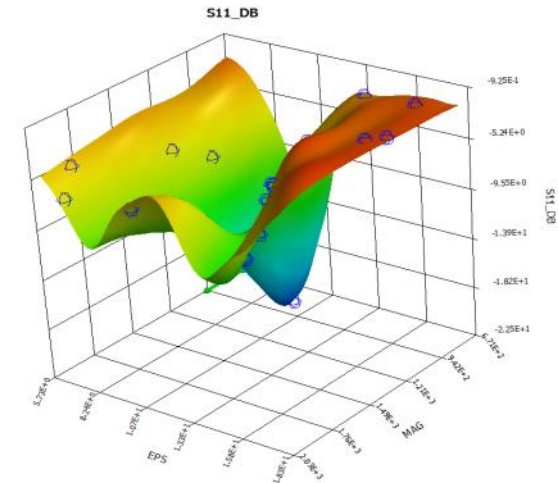
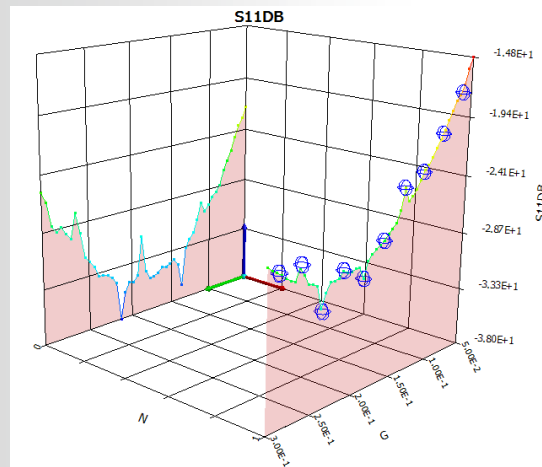
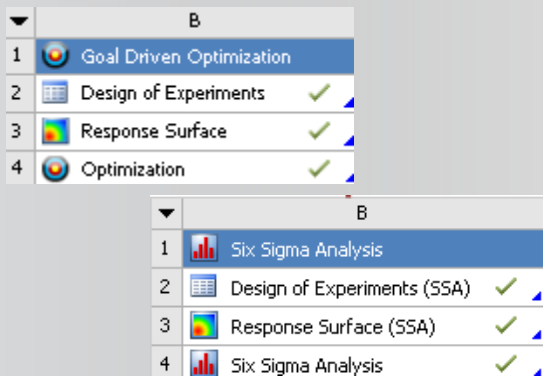
Using Workbench for Design Exploration

DesignXplorer (DX) is a tool for designing and understanding the analysis response of parts and assemblies

The Response Surface Method allows for optimization and six-sigma studies efficiently

DX uses Design of Experiments (DOE)

- DOE method determines how many, and which, design points should be solved for the most efficient approach to optimization
- Response surface is fit to solved DOE



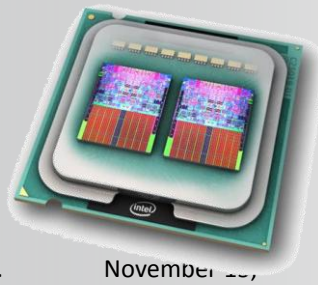
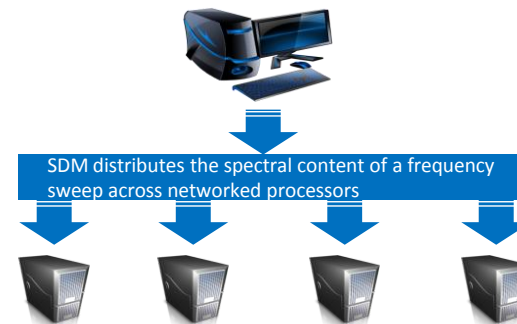
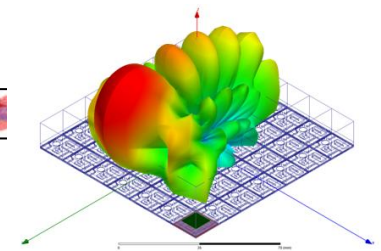
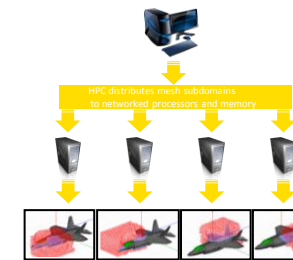
ANSYS High Performance Computing

- DSO – Distributed Solve Option

- DDM – Domain Decomposition Method
 - Feature of HPC licensing

- SDM – Spectral Decomposition Method
 - Feature of HPC licensing

- MPO – Multi-processing option
 - Feature of HPC licensing



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